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# Low-Noise, Low-Distortion, G = 2000 INSTRUMENTATION AMPLIFIER

#### **FEATURES**

LOW NOISE: 1.3nV/√Hz at 1kHz
 LOW THD+N: 0.09% at 1kHz
 WIDE BANDWIDTH: 450kHz

● WIDE SUPPLY RANGE: ±4.5V to ±18V

● HIGH CMR: > 100dB

GAIN SET WITH EXTERNAL RESISTOR
 SO-14 SURFACE-MOUNT PACKAGE

## **DESCRIPTION**

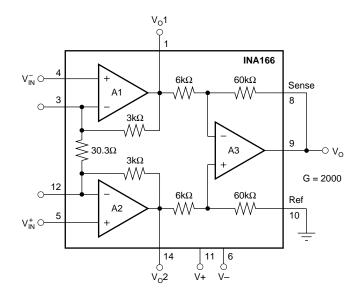
The INA166 is a very low-noise, low-distortion, monolithic instrumentation amplifier. Its current-feedback circuitry achieves very wide bandwidth and excellent dynamic response over a wide range of gain. It is ideal for low-level signals such as microphones or hydrophones. Many industrial, instrumentation, and medical applications also benefit from its low noise and wide bandwidth.

## APPLICATIONS

- MOVING-COIL TRANSDUCER AMPLIFIERS
- DIFFERENTIAL RECEIVERS
- BRIDGE TRANSDUCER AMPLIFIERS
- MICROPHONE AND HYDROPHONE PREAMPS

Unique distortion cancellation circuitry reduces distortion to extremely low levels, even in high gain. The INA166 provides near-theoretical noise performance for  $200\Omega$  source impedance. Its differential input, low noise, and low distortion provide superior performance as a low-level signal amplifier.

The INA166 is available in a space-saving SO-14 surface-mount package, specified for operation over the -40°C to +85°C temperature range.



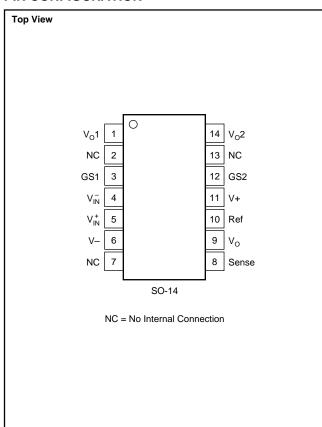


# SPECIFICATIONS: $V_S = \pm 5V$

 $T_A$  = +25°C and at rated supplies,  $V_S$  =  $\pm 5V$ ,  $R_L$  =  $2k\Omega$  connected to ground, G = 2000, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
GAIN						
Gain Error			±0.3	±1	%	
Gain Temp Drift Coefficient			±10		ppm/°C	
Nonlinearity			±0.005		% of FS	
INPUT REFERRED NOISE						
Voltage Noise	$R_{SOURCE} = 0\Omega$					
f <sub>O</sub> = 1kHz	COCKE		1.3		nV/√ <del>Hz</del>	
f <sub>O</sub> = 100Hz			1.6		nV/√Hz	
f <sub>O</sub> = 10Hz			2		nV/√ <del>Hz</del>	
Current Noise						
$f_O = 1 \text{kHz}$			0.8		pA/√Hz	
INPUT OFFSET VOLTAGE						
Input Offset Voltage	$V_{CM} = V_{OUT} = 0V$		±50	±250	μV	
vs Temperature	$T_A = T_{MIN}$ to $T_{MAX}$	1	±2.5		μV/°C	
vs Power Supply	$V_{S} = \pm 4.5 \text{V to } \pm 18 \text{V}$	1	±1	±3	μV/V	
INPUT VOLTAGE RANGE	13 = 101 10 = 101	<del> </del>			F	
Common-Mode Voltage Range	$V_{IN}^{+} - V_{IN}^{-} = 0V$	(V+) - 4	(V+) - 3		V	
Common wood vollage Italige	$V_{1N}^{I} - V_{1N}^{I} = 0V$ $V_{1N}^{I} - V_{1N}^{I} = 0V$	(V+) - 4 (V-) + 4	(V-) + 3		ľ	
Common-Mode Rejection	$V_{\text{CM}} = \pm 1V, R_{\text{SRC}} = 0\Omega$	100	120		dB	
·	V CM - ±1 V, 1\SRC - 052	100	120		ub.	
INPUT BIAS CURRENT			2.5	40		
Initial Bias Current			2.5	12	μΑ	
vs Temperature			15		nA/°C	
Initial Offset Current vs Temperature			0.1 0.5	1	μA nA/°C	
· · · · · · · · · · · · · · · · · · ·			0.5		TIA/ C	
INPUT IMPEDANCE	Differential		60  2		MΩ  pF	
	Differential Common-Mode		60  2		MΩ  pF   MΩ  pF	
DYNAMIC RESPONSE			33112			
Bandwidth, Small Signal, –3dB			450		kHz	
Slew Rate			15		V/µs	
THD+Noise, f = 1kHz			0.09		%	
Settling Time, 0.1%	5V Step		2.5		π <sub>76</sub> μs	
0.01%	5V Step		3.5			
Overload Recovery	50% Overdrive		1		μs μs	
•	0070 Overdilive	<del> </del>	'		μο	
<b>OUTPUT</b> Voltage	$R_L = 2k\Omega$ to Ground	(V+) - 2	(V+) - 1.8		V	
vollage	K <sub>L</sub> = 2ks2 to Glound	(V+) - 2 (V-) + 2			ľ	
Load Capacitance Stability		(v-) + 2	(V-) + 1.8 1000		pF	
Short-Circuit Current	Continuous-to-Common		±60		рг mA	
POWER SUPPLY					,	
Rated Voltage			±5		V	
Voltage Range		±4.5	1.5	±18	l v	
Current, Quiescent	I <sub>O</sub> = 0mA	14.5	±10	±10 ±12	mA	
	10 = 0111A	-	±10	±12	IIIA	
TEMPERATURE RANGE		40		.05		
Specification		-40 40		+85	°C	
Operating		-40	400	+125	°C	
Thermal Resistance, $\theta_{\mathrm{JA}}$			100		°C/W	
		[			1	
		[			1	
					1	

#### **PIN CONFIGURATION**





This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### ABSOLUTE MAXIMUM RATINGS(1)

	Power Supply Voltage	±18V
١	Signal Input Terminals, Voltage(2)	(V-) - 0.5V to $(V+) + 0.5V$
۱	Current <sup>(2)</sup>	10mA
۱	Output Short-Circuit to Ground	Continuous
۱	Operating Temperature	55°C to +125°C
۱	Storage Temperature	55°C to +125°C
۱	Junction Temperature	+150°C
	Lead Temperature (soldering, 10s)	+300°C

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied. (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.

#### PACKAGE/ORDERING INFORMATION

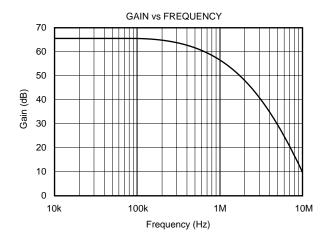
PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER	PACKAGE MARKING	ORDERING NUMBER <sup>(1)</sup>	TRANSPORT MEDIA
INA166UA	SO-14 Surface Mount	235	INA166UA "	INA166UA INA166UA/2K5	Rails Tape and Reel

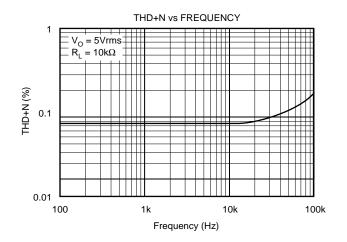
NOTE: (1) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /2K5 indicates 2500 devices per reel). Ordering 2500 pieces of "INA166UA/2K5" will get a single 2500-piece Tape and Reel.

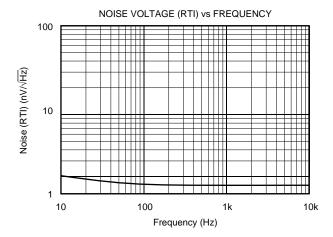


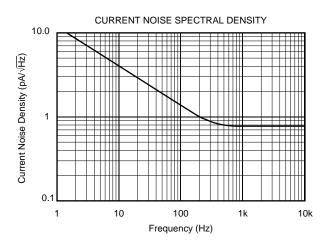
# **TYPICAL PERFORMANCE CURVES**

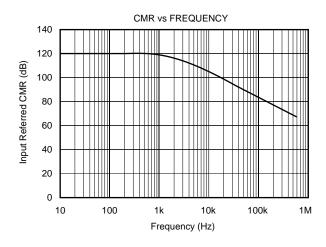
At  $T_A$  = +25°C,  $V_S$  = ±5V,  $R_L$  = 2k $\Omega$ ,  $C_L$  = 50pF, G = 2000, unless otherwise noted.

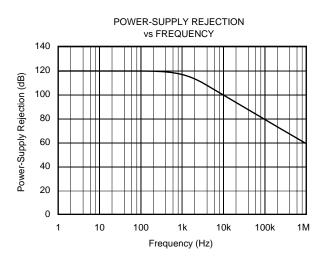








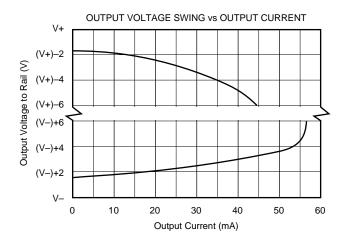


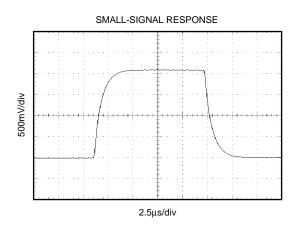


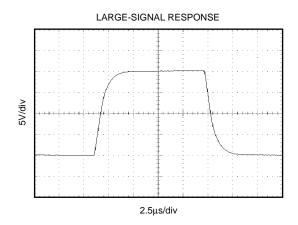


# **TYPICAL PERFORMANCE CURVES (Cont.)**

At T\_A = +25°C, V\_S =  $\pm 5$ V, R\_L = 2k $\Omega$ , C\_L = 50pF, G = 2000, unless otherwise noted.









## APPLICATIONS INFORMATION

Figure 1 shows the basic connections required for operation. Power supplies should be bypassed with  $0.1\mu F$  tantalum capacitors near the device pins. The output Sense (pin 8) and output Reference (pin 10) should be low-impedance connections. Resistance of greater than  $5\Omega$  in series with these connections will degrade the common-mode rejection of the INA166.

#### **GAIN**

Gain of the INA166 is internally set for G = 2000. Input stage (A1, A2) gain is 200 and the output stage gain (A3) is 10. Internal resistor values are laser trimmed for accurate ratios to achieve excellent gain accuracy and common-mode rejection, but absolute resistor values are approximately  $\pm 20\%$ . Nominal resistor values are shown.

Although the INA166 is primarily intended for fixed-gain applications, the gain can be increased by connecting a gain-set resistor,  $R_G$ , between pin 3 and pin 12 The nominal gain will be:

$$G = 2000 + \frac{60000}{R_G}$$

Accuracy of the 60000 term in this equation is approximately  $\pm 20\%$ . The stability and temperature drift of  $R_G$  contributes to the overall gain accuracy and these effects can be inferred from this gain equation.

#### **NOISE PERFORMANCE**

The INA166 provides very low-noise with low-source impedance. Its  $1.3 \text{nV}/\sqrt{\text{Hz}}$  voltage noise delivers near-theoretical noise performance with a source impedance of  $200\Omega$ .

The input stage design used to achieve this low noise, results in relatively high input bias current and input bias current noise. As a result, the INA166 may not provide the best noise performance with a source impedance greater than  $10k\Omega$ . For source impedance greater than  $10k\Omega$ , other instrumentation amplifiers may provide improved noise performance.

#### INPUT CONSIDERATIONS

Very low source impedance (less than  $10\Omega$ ) can cause the INA166 to oscillate. This depends on circuit layout, signal source, and input cable characteristics. An input network consisting of a small inductor and resistor, as shown in Figure 2, can greatly reduce any tendency to oscillate. This is especially useful if a variety of input sources are to be connected to the INA166. Although not shown in other figures, this network can be used as needed with all applications shown.

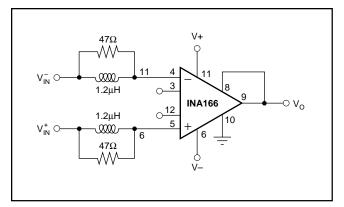


FIGURE 2. Input Stabilization Network.

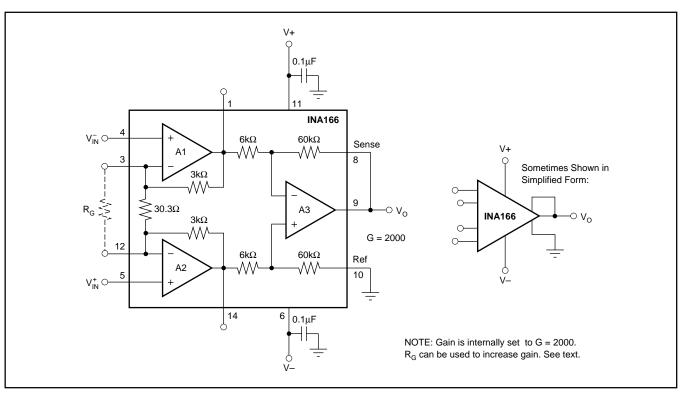


FIGURE 1. Basic Circuit Connections.

#### **OFFSET VOLTAGE TRIM**

A variable voltage applied to pin 10, as shown in Figure 3, can be used to adjust the output offset voltage. A voltage applied to pin 10 is summed with the output signal. An op amp connected as a buffer is used to provide a low impedance at pin 10 to assure good common-mode rejection.

#### **OUTPUT SENSE**

An output sense terminal allows greater gain accuracy in driving the load. By connecting the sense connection at the load, I • R voltage loss to the load is included inside the feedback loop. Current drive can be increased by connecting a buffer amp inside the feedback loop, as shown in Figure 4.

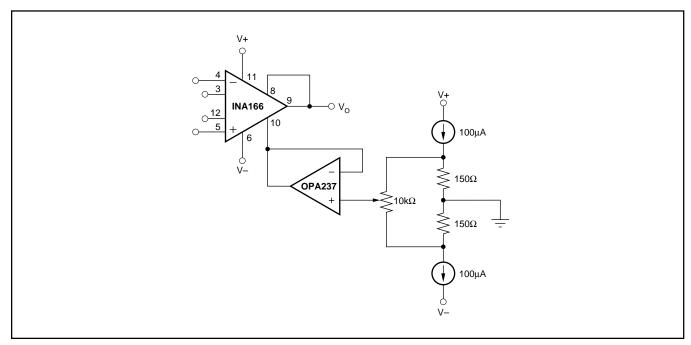


FIGURE 3. Offset Voltage Adjustment Circuit.

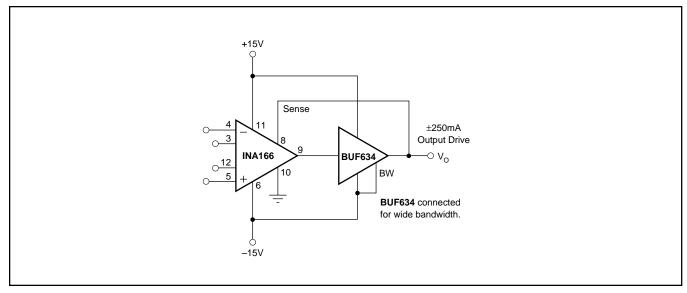


FIGURE 4. Buffer for Increase Output Current.

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#### PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
INA166UA	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-55 to 125	INA166UA
INA166UA/2K5	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-55 to 125	INA166UA
INA166UA/2K5.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-55 to 125	INA166UA

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

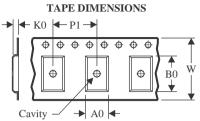
<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA166UA/2K5	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

# **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

Ì	Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	INA166UA/2K5	SOIC	D	14	2500	353.0	353.0	32.0	

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